

PROCESS FOR MANUFACTURING ELECTRONIC-COMPONENT
PACKAGES AND ELECTRONIC-COMPONENT PACKAGE OBTAINED BY
MEANS OF THIS PROCESS

5

Abstract

The invention relates to a process for manufacturing integrated-circuit packages (110), wherein a cavity is produced in a strip of dielectric material covered with a sheet of electrically conductive material. An electronic component
10 (90) is placed in the cavity and encapsulated by at least partially filling the cavity with an encapsulation material (100). The bottom of the blind cavity being formed from a layer of flexible and removable material that is removed after encapsulation. The invention also relates to integrated-circuit packages (110) manufactured using this process. These integrated-circuit packages (110) are for
15 example QFN packages.

(Fig. 5)